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Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 May 26 2003 Mar 25



## Product data sheet

# BAT17

## FEATURES

- Low forward voltage
- Small SMD package
- · Low capacitance.

#### **APPLICATIONS**

- UHF mixer
- · Sampling circuits
- Modulators
- Phase detection.

## DESCRIPTION

Planar Schottky barrier diode in a small SOT23 plastic SMD package.

#### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>	
BAT17	A3*	

#### Note

- 1. \* = p : Made in Hong Kong.
  - \* = t : Made in Malaysia.
  - \* = W : Made in China.

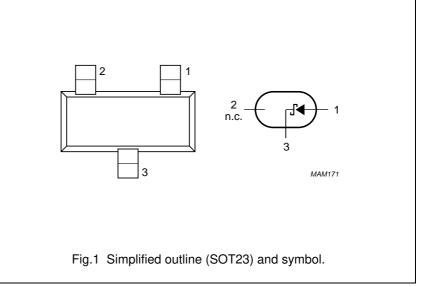
### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage	-	4	V
I <sub>F</sub>	continuous forward current	-	30	mA
T <sub>stg</sub>	storage temperature	-65	+150	°C
Tj	junction temperature	_	100	°C

#### PINNING

PIN	DESCRIPTION
1	anode
2	not connected
3	cathode



BAT17

## ELECTRICAL CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.2		
		I <sub>F</sub> = 0.1 mA	350	mV
		I <sub>F</sub> = 1 mA	450	mV
		I <sub>F</sub> = 10 mA	600	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 3 V; see Fig.3	0.25	μA
		$V_R = 3 \text{ V}; \text{ T}_{amb} = 60 \text{ °C}; \text{ see Fig.3}$	1.25	μA
r <sub>D</sub>	diode forward resistance	f = 1 kHz; I <sub>F</sub> = 5 mA	15	Ω
C <sub>d</sub>	diode capacitance	$f = 1 MHz; V_R = 0; see Fig.4$	1	pF
F	noise figure	f = 900 MHz; note 1	8	dB

#### Note

1. The local oscillator is adjusted for a diode current of 2 mA. IF amplifier noise  $F_{if}$  = 1.5 dB; f = 35 MHz.

## THERMAL CHARACTERISTICS

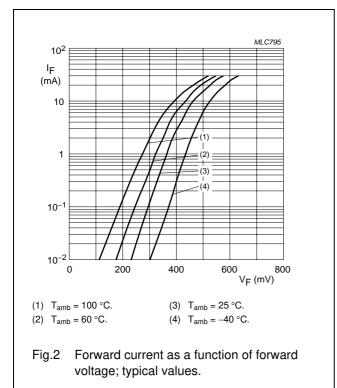
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Refer to SOT23 standard mounting conditions.

## BAT17

#### **GRAPHICAL DATA**



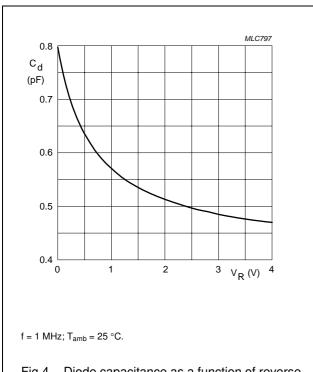
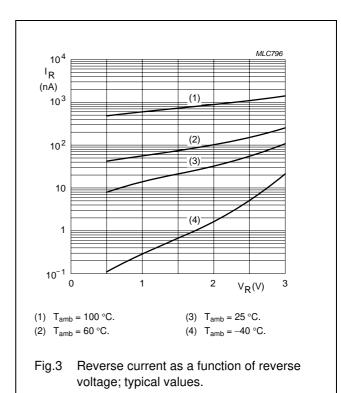


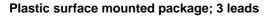
Fig.4 Diode capacitance as a function of reverse voltage; typical values.

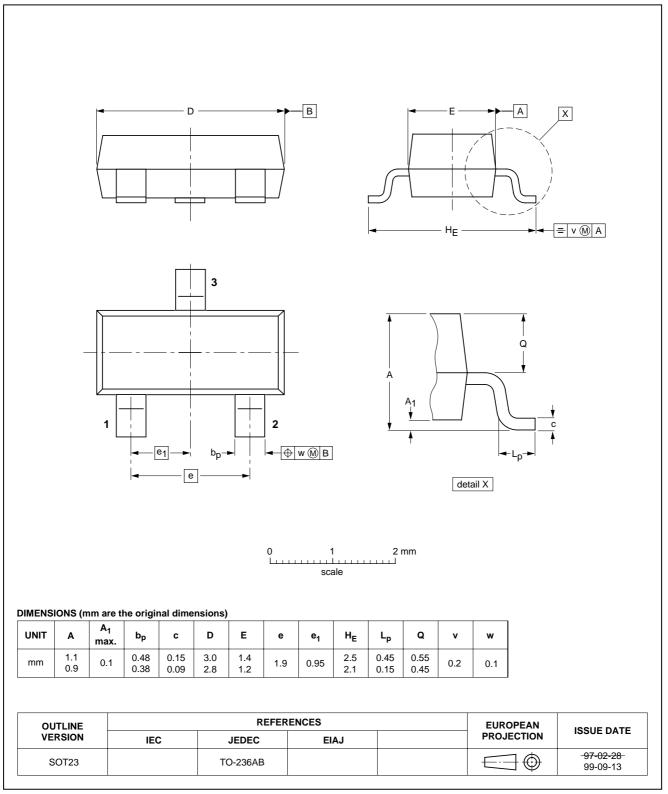


**BAT17** 

# Schottky barrier diode

#### PACKAGE OUTLINE





SOT23

BAT17

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### DATA SHEET STATUS

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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# NXP Semiconductors

#### **Customer notification**

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#### **Contact information**

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Printed in The Netherlands

613514/03/pp7

Date of release: 2003 Mar 25

Document order number: 9397 750 10963

